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Substrate: 2.36mm ±0.18mm [0.093" ±0.007"] FR4/G10 or equivalent high temp material. (RoHS)

2

Pins: shell material- Brass Alloy 360 1/2 hard; shell finish-0.25µm [10µ"] Au over 2.54µm [100µ"] Ni (min.). Contact material- BeCu alloy 172, HT; contact finish 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

Side View

Description: Giga-snaP BGA extender.

516 position (0.80mm pitch) gold plated female receptacle to male terminals.

	C11504 Drawing	Status: Released	Scale:	_3:1	Rev: A	
3	© 2012 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: M. Tully	Drawing: M. Tully		Date: 8/6/12	
		File: C11504 Dwg.mcd	File: C11504 Dwg.mcd		Modified:	



Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.18mm [±0.007"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.